

XBP06V4E4GR-G

ETR29003-006

Transient Voltage Suppressor (TVS)

■ GENERAL DESCRIPTION

Four elements in USP-4 package (Anode Common)
High ESD

■ ABSOLUTE MAXIMUM RATINGS

Ta=25°C

PARAMETER	SYMBOL	RATINGS	UNITS
Peak Pulse Power (*1)	Ppk	70	W
Power Dissipation	Pd	120	mW
		1000 (*2)	
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55~150	°C
ESD Durability (*3)(*4)	Vpp	30	kV
Contact Discharge			

(*1): tp=8/20 μs

(*2): This is a reference data taken by using the test board.

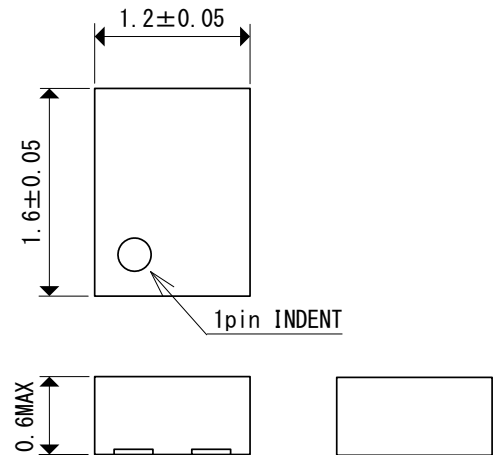
(*3): Test Condition IEC61000-4-2 Standard

(*4): Criterion: No damage to device elements

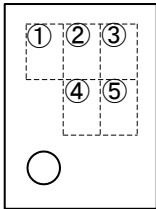
■ APPLICATIONS

ESD protection

■ PACKAGING INFORMATION



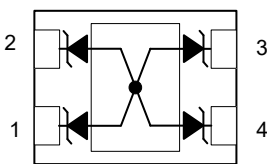
■ MARKING RULE



①②③ : BP2(Product Number)

④⑤ : Lot Number

■ PIN CONFIGURATION



BOTTOM VIEW

1. Cathode
 2. Cathode
 3. Cathode
 4. Cathode
- TAB. Anode

■ PRODUCT NAME

PRODUCT NAME	PACKAGE	ORDER UNIT
XBP06V4E4GR-G*	USP-4	3,000/Reel

* The "-G" suffix indicates that the products are Halogen and Antimony free as well as being fully RoHS compliant.

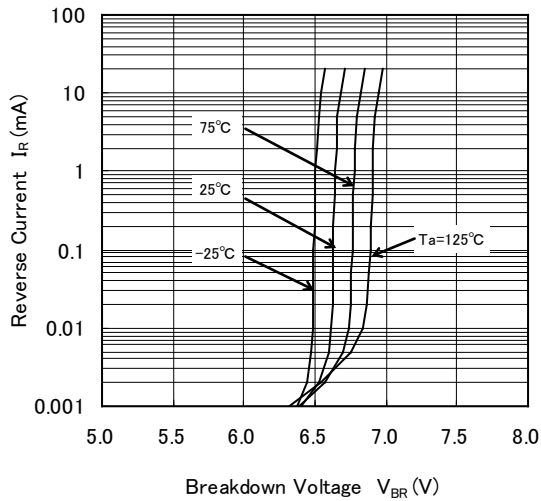
■ ELECTRICAL CHARACTERISTICS

Ta=25°C

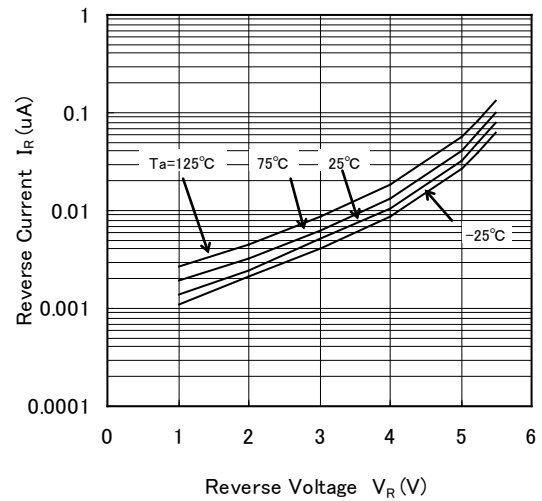
PARAMETER	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNITS
Breakdown Voltage	V _{BR}	I _R =5mA	6.4	6.8	7.2	V
Leakage Current	I _{RM}	V _{RM} =5V	-	-	1.0	μA
Forward Voltage	V _F	I _F =10mA	-	-	1.25	V
Inter-Terminal Capacity	C _i	V _R =0V, f=1MHz	-	40	-	pF

TYPICAL PERFORMANCE CHARACTERISTICS

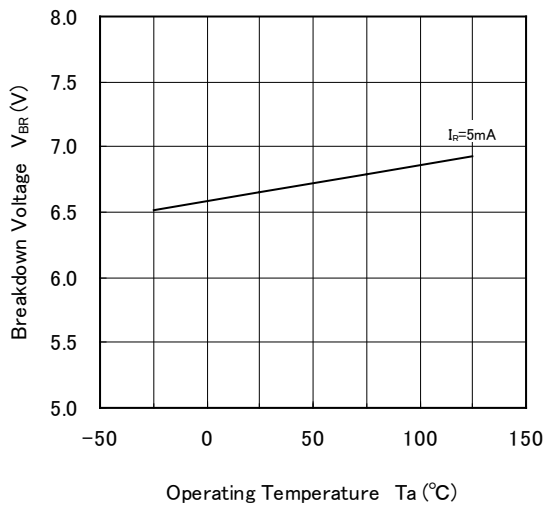
(1) Reverse Current vs. Breakdown Voltage



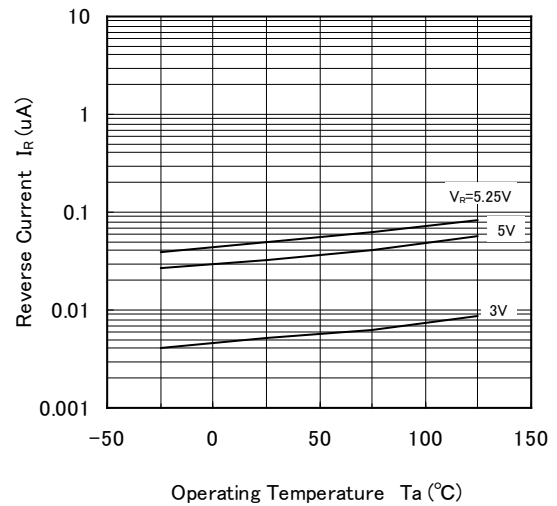
(2) Reverse Current vs. Reverse Voltage



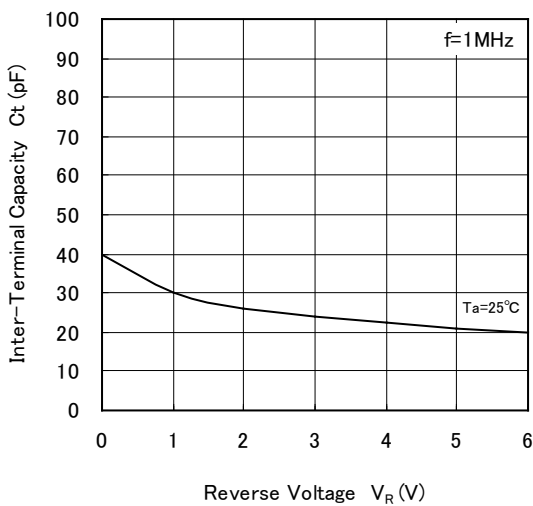
(3) Breakdown Voltage vs. Operating Temperature



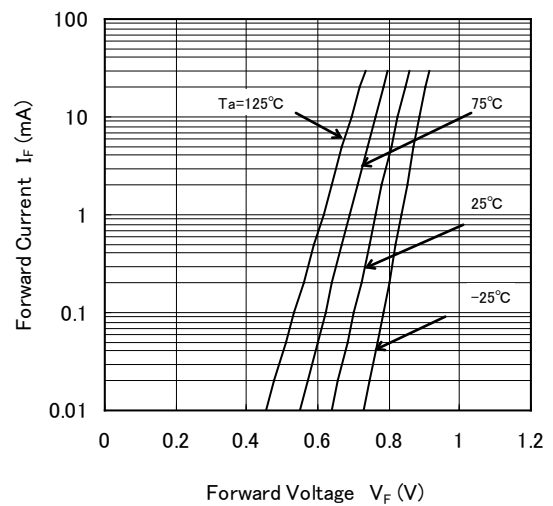
(4) Reverse Current vs. Operating Temperature



(5) Inter-Terminal Capacity vs. Reverse Voltage



(6) Forward Current vs. Forward Voltage



■PACKAGING INFORMATION

For the latest package information go to, www.torexsemi.com/technical-support/packages

PACKAGE	OUTLINE / LAND PATTERN	THERMAL CHARACTERISTICS
USP-4	USP-4 PKG	USP-4 Power Dissipation

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